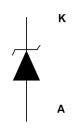


400 W TVS in STmite Flat





Unidirectional

Product status link							
SMM4F	SMM4F5.0A, SMM4F6.0A, SMM4F6.5A, SMM4F8.5A, SMM4F10A, SMM4F12A, SMM4F13A, SMM4F15A, SMM4F18A, SMM4F20A, SMM4F24A, SMM4F26A, SMM4F28A, SMM4F33A						

Features

- Peak pulse power: 400 W (10/1000 μs) and 2.5 kW (8/20 μs)
- Flat and thin package: 0.85 mm
- Stand-off voltage range from 5 V to 33 V
- Unidirectional type
- Low leakage current: 0.2 μA at 25 °C and 1 μA at 85 °C
- Operating T_i max: 175 °C
- High power capability at T_i max.: up to 160 W (10/1000 μs)
- · Lead finishing: matte tin plating

Complies with the following standards

- UL94, V0
- J-STD-020 MSL level 1
- J-STD-002, JESD 22-B102 E3 and MIL-STD-750, method 2026
- JESD-201 class 2 whisker test
- IPC7531 footprint and JEDEC registered package outline
- IEC 61000-4-2, C = 150 pF R = 330 Ω exceeds level 4:
 - 30 kV (contact discharge)
 - 30 kV (air discharge)
- IEC 61000-4-4
 - 4 kV

Description

The SMM4F TVS series are designed to protect sensitive circuits against transient surges.

The planar technology makes it compatible with high-end circuits where low leakage current and high junction temperature are required to provide long term reliability and stability.



1 Characteristics

Table 1. Absolute maximum ratings (T_{amb} = 25 °C)

Symbol		Parameter	Value	Unit
		IEC 61000-4-2 (C = 150 pF, R = 330 Ω)		
V _{PP}	Peak pulse voltage	Contact discharge	30	kV
		Air discharge	30	
P _{PP}	Peak pulse power dissipation	10/1000 μs, T _j initial = T _{amb}	400	W
T _{stg}	Storage temperature range	-65 to +175	°C	
Tj	Operating junction temperature range	-55 to +175	°C	
T _L	Maximum lead temperature for solderi	260	°C	

Figure 1. Electrical characteristics - parameter definitions

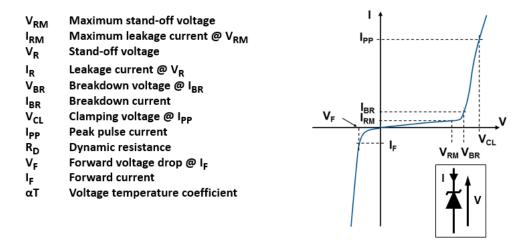
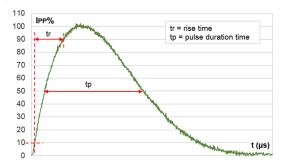


Figure 2. Pulse definition for electrical characteristics



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Table 2. Electrical characteristics - parameter values (T_{amb} = 25 °C, unless otherwise specified)

	I _{RM} max at V _{RM}		Lou may at Vou				10 / 1000 μs		8 / 20 μs			αΤ		
			V _{BR} at I _{BR} ⁽¹⁾		V _{CL} ⁽²⁾⁽³⁾ I _{PP} ⁽⁴⁾ R _D		V _{CL} ⁽²⁾⁽³⁾ I _{PP} ⁽⁴⁾		R _D	R _D				
Type	25 °C	85 °C		Min.	Тур.	Max.		Max.		Max.	Max.		Max.	Max.
	μ	A	V	V mA		V	Α	Ω	V Α Ω		Ω	10 ⁻⁴ /°C		
SMM4F5.0A	10	50	5.0	6.46	6.80	7.14	10	9.2	43.5	0.047	13.4	179	0.035	5.7
SMM4F6.0A	10	50	6.0	6.65	7.00	7.35	10	10.3	38.8	0.076	13.7	175	0.036	5.9
SMM4F6.5A	10	50	6.5	7.13	7.50	7.88	10	11.2	35.7	0.093	14.5	166	0.040	6.1
SMM4F8.5A	10	50	8.5	9.5	10.0	10.5	1	14.4	27.7	0.141	19.5	140	0.064	7.3
SMM4F10A	0.2	1	10	11.4	12.0	12.6	1	17.0	23.5	0.188	21.7	127	0.072	7.8
SMM4F12A	0.2	1	12	13.3	14.0	14.7	1	19.9	20.1	0.259	25.3	112	0.095	8.3
SMM4F13A	0.2	1	13	14.3	15.0	15.8	1	21.5	18.6	0.306	27.2	106	0.108	8.4
SMM4F15A	0.2	1	15	17.1	18.0	18.9	1	24.4	16.4	0.335	32.5	90	0.151	8.8
SMM4F18A	0.2	1	18	20.9	22.0	23.1	1	29.2	14.0	0.436	39.3	76	0.213	9.2
SMM4F20A	0.2	1	20	22.8	24.0	25.2	1	32.4	12.0	0.600	42.8	70	0.250	9.4
SMM4F24A	0.2	1	24	26.6	28.0	29.4	1	38.9	9.5	1.00	50	61	0.338	9.6
SMM4F26A	0.2	1	26	28.5	30.0	31.5	1	42.1	9.0	1.18	53.5	58	0.380	9.7
SMM4F28A	0.2	1	28	31.4	33.0	34.7	1	45.4	8.0	1.34	59	53	0.458	9.8
SMM4F33A	0.2	1	33	37.1	39.0	41.0	1	53.3	7.0	1.76	69.7	45	0.638	10

^{1.} To calculate V_{BR} versus T_j : V_{BR} at T_J = V_{BR} at 25 °C x (1 + αT x (T_j - 25))

^{2.} To calculate V_{CL} versus T_j : V_{CL} at T_J = V_{CL} at 25 °C x (1 + αT x (T_j - 25))

^{3.} To calculate V_{CLmax} versus $I_{PPappli}$: $V_{CLmax} = V_{BR \ max} + R_D \ x \ I_{PPappli}$

^{4.} Surge capability given for both directions



1.1 Characteristics (curves)

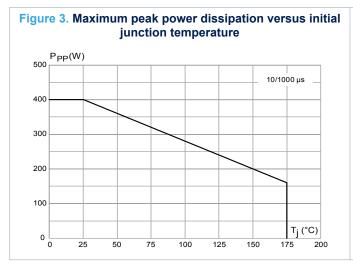


Figure 4. Maximum peak pulse power versus exponential pulse duration

Ppp (W)

V_{RM} ≤ 6.5 V
V_{RM} > 6.5 V
V_{RM} >

10

Figure 6. Dynamic resistance versus pulse duration

R_D (Ω)

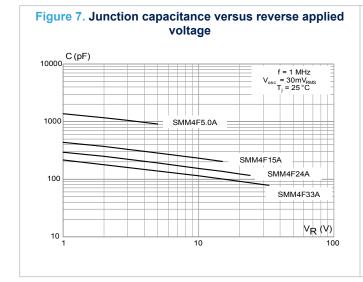
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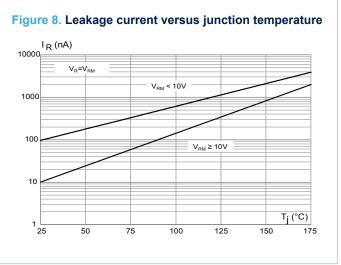
SMM4F15A

SMM4F5.0A

O.01

O.

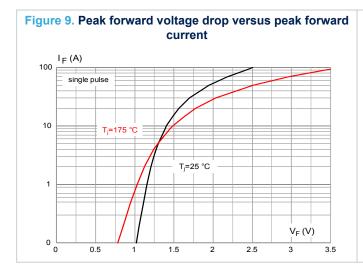




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100





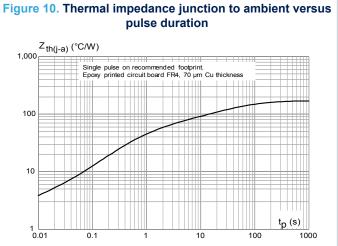
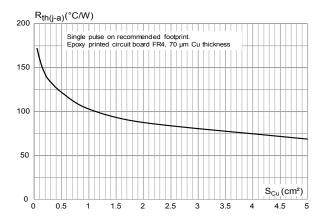


Figure 11. Thermal resistance junction to ambient versus copper surface under each lead



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2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 STmite Flat package information

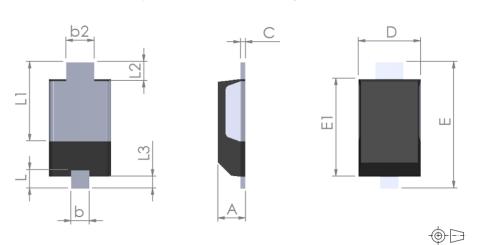


Figure 12. STmite Flat package outline

Table 3. STmite Flat mechanical data

	Dimensions								
Ref.		Millimeters		Inches					
	Min.	Тур.	Max.	Min.	Тур.	Max.			
А	0.80	0.85	0.95	0.031	0.033	0.038			
b	0.40	0.55	0.65	0.015	0.022	0.026			
b2	0.70	0.85	1.00	0.027	0.033	0.040			
С	0.10	0.15	0.25	0.003	0.006	0.010			
D	1.75	1.90	2.05	0.068	0.075	0.081			
E	3.60	3.80	3.90	0.141	0.150	0.154			
E1	2.80	2.95	3.10	0.110	0.116	0.123			
L	0.50	0.55	0.80	0.019	0.022	0.032			
L1	2.10	2.40	2.60	0.082	0.094	0.103			
L2	0.45	0.60	0.75	0.017	0.024	0.030			
L3	0.20	0.35	0.50	0.007	0.014	0.020			

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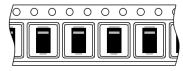


Figure 13. Footprint recommendations, dimensions in mm (inches) 1.8 (0.070)

Figure 14. Marking layout (refer to ordering information table for marking) Cathode bar ww M M M M MMMM: Marking Y : Year WW : week

0.8 0.55 (0.021)0.7 (0.027)

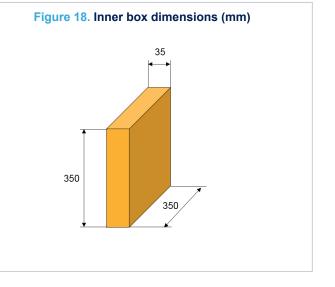
Figure 15. Package orientation in reel



Taped according to EIA-481 Note: Pocket dimensions are not on scale Pocket shape may vary depending on package On bidirectional devices, marking and logo may be not always in the same direction

Figure 16. Tape and reel orientation Maximum cover tape thickness 0.1 mm Sprocket hole

Figure 17. Reel dimensions (mm) Ø 330 max 18.4 2 ± 0.5 Ø 13 Ø 100 Ø 20.2 min



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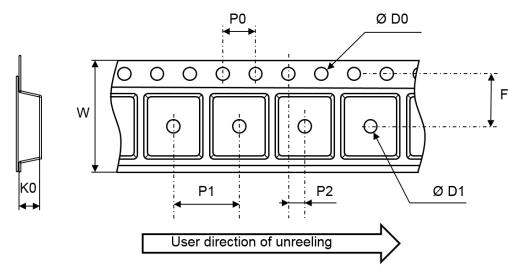


Figure 19. Tape and reel outline

Note: Pocket dimensions are not on scale
Pocket shape may vary depending on package

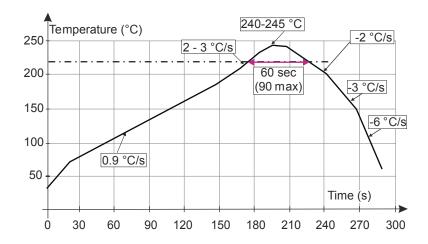
Table 4. Tape and reel mechanical data

	Dimensions							
Ref.	Millimeters							
	Min.	Тур.	Max.					
P0	3.9	4	4.1					
P1	3.9	4	4.1					
P2	1.9	2	2.1					
ØD0	1.5	1.55	1.6					
ØD1	1.5							
F	5.4	5.5	5.6					
K0	1.0	1.1	1.2					
W	11.7	12	12.3					

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Figure 20. ST ECOPACK recommended soldering reflow profile for PCB mounting



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3 Ordering information

Figure 21. Ordering information scheme

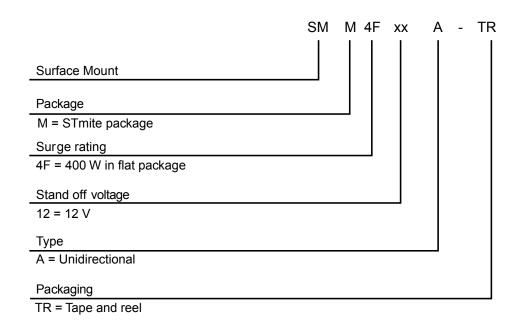


Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
SMM4FxxA-TR	See Table 6. Marking.	STmite Flat	16 mg	12000	Tape and reel

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Table 6. Marking

Order code	Marking
SMM4F5.0A-TR	4UA
SMM4F6.0A-TR	4UB
SMM4F6.5A-TR	4UC
SMM4F8.5A-TR	4UD
SMM4F10A-TR	4UE
SMM4F12A-TR	4UF
SMM4F13A-TR	4UG
SMM4F15A-TR	4UH
SMM4F18A-TR	4UJ
SMM4F20A-TR	4UK
SMM4F24A-TR	4UM
SMM4F26A-TR	4UN
SMM4F28A-TR	4UO
SMM4F33A-TR	4UQ



Revision history

Table 7. Document revision history

Date	Version	Changes
29-Nov-2007	1	First issue.
19-Dec-2007	2	Updated I _{PP} and R _D parameters in columns 10 and 11 of Table 4.
19-Aug-2014	3	Updated package name.
19-Jan-2017	4	Updated cover page and Table 4.
03-Mar-2020	5	Updated document title, Section Description, Section 1 Characteristics and Section 1.1 Characteristics (curves).
15-Apr-2020	6	Updated Figure 5 and Figure 11.



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